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PULL OUT PRODUCT, TO-BE PRODUCT

REMOVE DEVICE STRUCTURE FILM

SELECTIVE ETCHING TO EXPOSE CRYSTAL DEFECT

AFTER-TREATMENT (SURFACE IMPURITIES REMOVING TREATMENT)

CLEANING (PARTICLE REMOVAL)

IMAGE RECOGNITION AND DEFECT EVALUATION

DEFECT QUANTIFICATION

FIG. 1

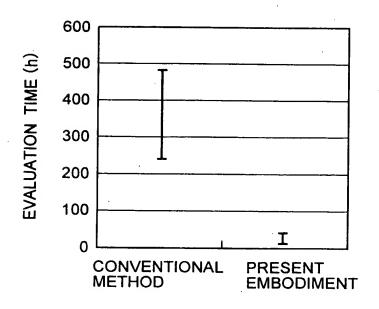
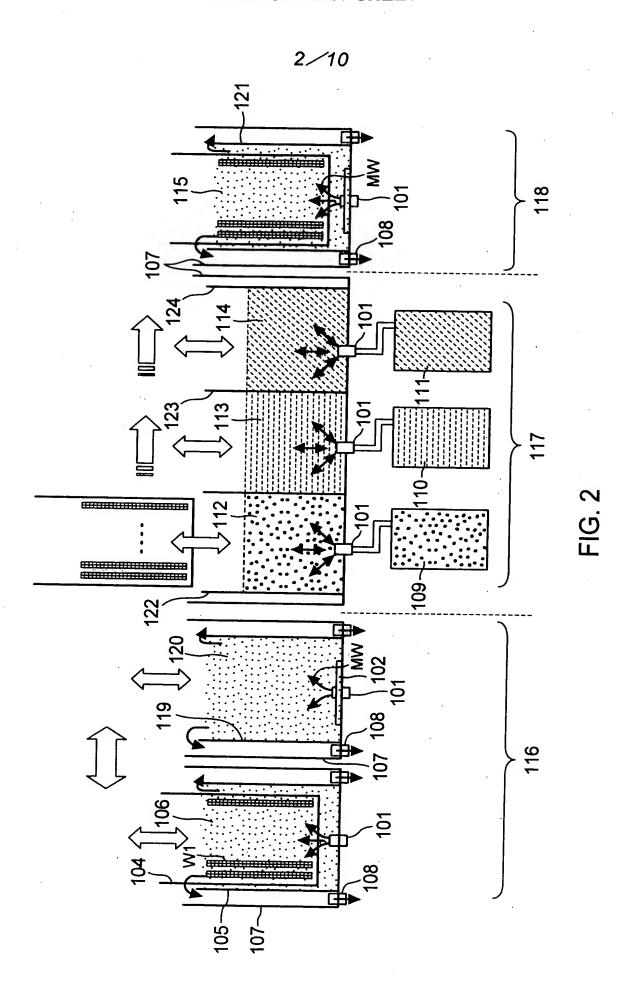
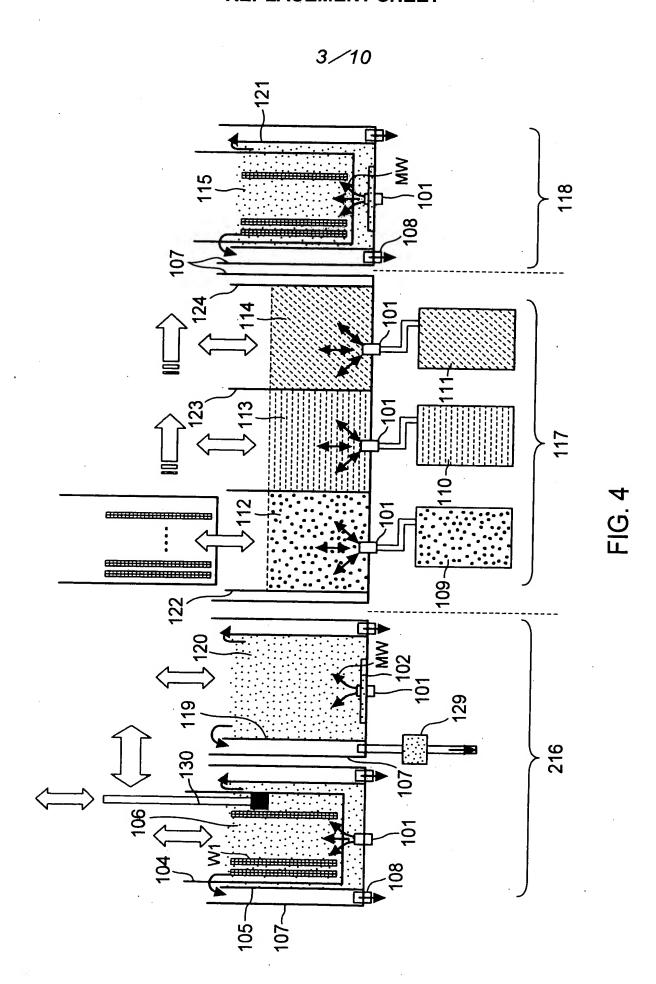


FIG. 3

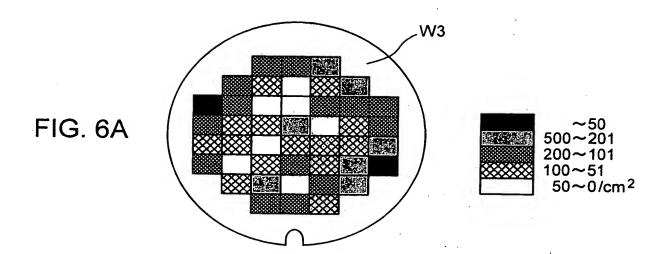


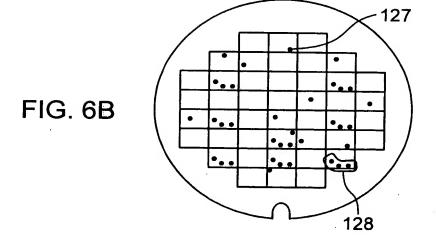


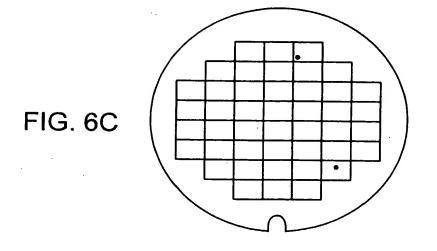
\bigvee	PULL OUT PRODUCT, TO-BE PRODUCT, TEG WAFER
\Diamond	REMOVE DEVICE STRUCTURE FILM
\Diamond	AFTER-TREATMENT (SURFACE IMPURITIES REMOVING TREATMENT)
\Diamond	CLEANING (PARTICLE REMOVAL)
\Diamond	IMAGE RECOGNITION AND DEFECT EVALUATION
	DEFECT QUANTIFICATION 1
\Diamond	SELECTIVE ETCHING TO EXPOSE CRYSTAL DEFECT
\Diamond	AFTER-TREATMENT (SURFACE IMPURITIES REMOVING TREATMENT)
\Diamond	CLEANING (PARTICLE REMOVAL)
\Diamond	IMAGE RECOGNITION AND DEFECT EVALUATION
	DEFECT QUANTIFICATION 2
	(DEFECT QUANTIFICATION 2) - (DEFECT QUANTIFICATION 1)

FIG. 5









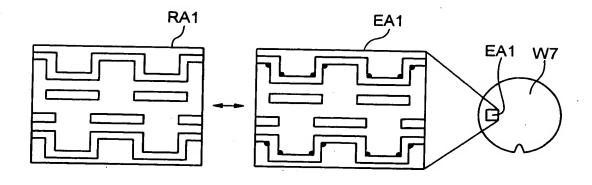


FIG. 7

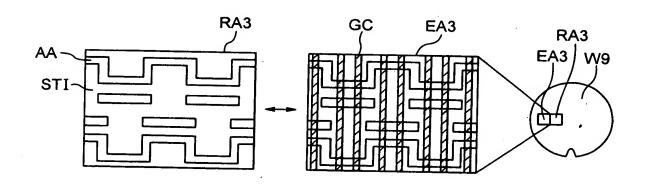


FIG. 8

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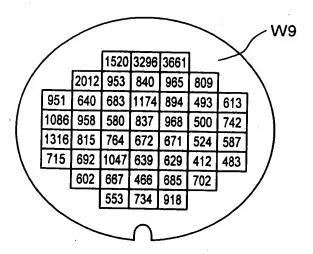


FIG. 9

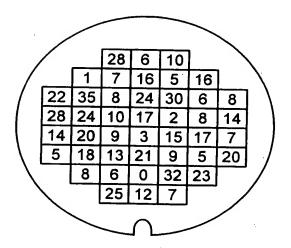


FIG. 10

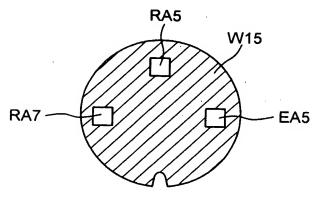


FIG. 11

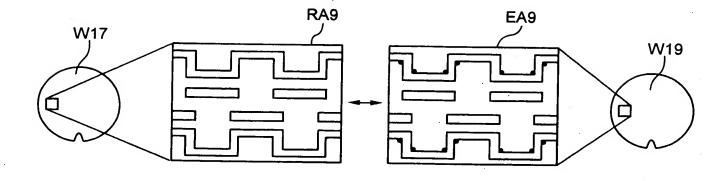


FIG. 12

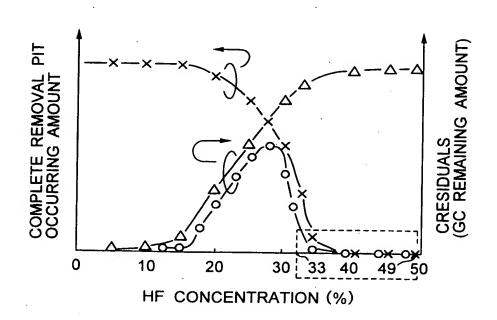


FIG. 13

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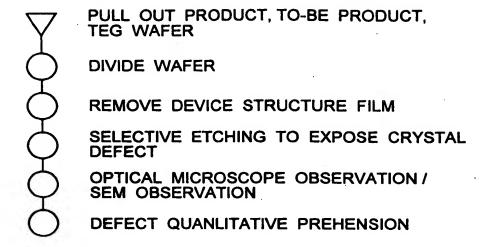


FIG. 14 (PRIOR ART)

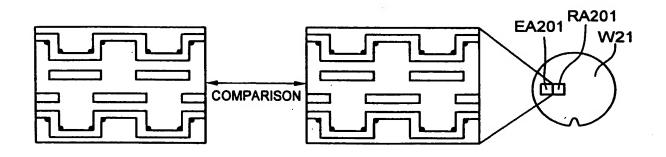


FIG. 16 (PRIOR ART)

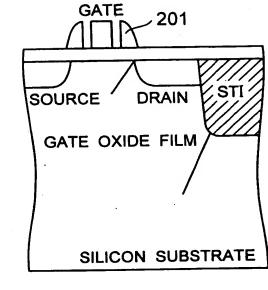
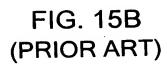


FIG. 15A (PRIOR ART)



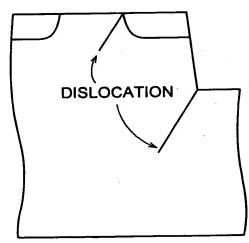


FIG. 15C (PRIOR ART)

